

ABSTRACT

A device for preventing errors during semiconductor wafer fabrication can be configured to prevent separation of optical sensor unit components, such as a gas supply pipe and a fixing guide, that could be caused by excess N₂ gas pressure. The device can also be configured to prevent excess moisture build-up that can lead to wafer sensing errors. The device includes a bath for receiving pure water or chemicals to remove particles. The bath can be further configured to discharge waste water after removal of the particles. Fixing guides are disposed at the outside of the bath to fix optical fiber sensors thereto. Optical fiber sensors are inserted into gas supply pipes, partially secured within the fixing guides. Purge output holes are formed at predetermined locations along the fixing guides to release N₂ gas pressure. A method for releasing excess pressure and a method for discharging excess moisture from an optical sensor unit are also provided.